

Power line chokes

Current-compensated SMD ring core double chokes 250 V AC, 1.1 ... 22 mH, 0.3 ... 2 A, + 40 °C

Series/Type: B82720S

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Current-compensated ring core double chokes



Rated voltage 250 V AC Nominal inductance 1.1 ... 22 mH Rated current 0.3 ... 2 A / +40 °C

Construction

- Current-compensated ring core double choke
- Ferrite core with epoxy coating (UL 94 V-0)
- Plastic case (UL 94 V-0)
- Silicone glue
- Sector winding

Features

- Approx. 0.7% stray inductance for differential-mode interference suppression
- Suitable for reflow soldering
- Design complies with EN 60938-2 (VDE 0565-2)
- RoHS-compatible

Applications

- Suppression of common-mode interferences
- Compact electronic ballasts in lamps
- Compact switch-mode power supplies

Terminals

- Base material CuSn6
- Layer composition Ni, Sn
- Hot-dipped

Marking

- Marking on component: Product brand (EPCOS), ordering code, rated inductance, rated current, graphic symbol, rated voltage, date of manufacture (YYWWD), production place identification code
- Minimum data on reel: Product brand, ordering code, rated inductance, rated current, quantity, date of packing

Delivery mode and packing unit

- 24-mm blister tape, wound on 330-mm Ø reel
- Packing unit: 250 pcs./reel

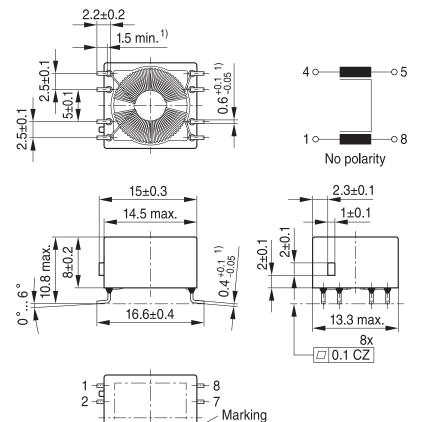




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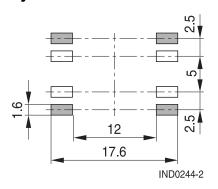
Dimensional drawing and pin configuration



<u>.</u> ⊶6

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Layout recommendation



Part tolerances to ISO 2768-C / ISO 8015. Size ISO 14405 (E) All dimensions in mm

IND2158-9-E

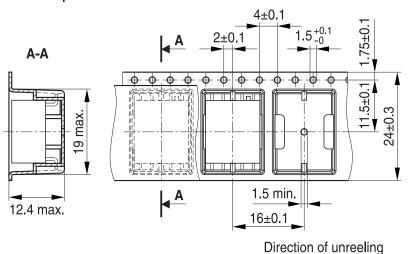
1) Soldering area

IND2135-6-E

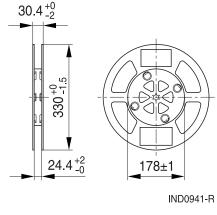
Taping and packing

3 -€

Blister tape



Reel



All dimensions in mm

IND0942-S-E



Current-compensated ring core double chokes



Technical data and measuring conditions

Rated voltage V _R	250 V AC (50/60 Hz)				
Test voltage V _{test}	1500 V AC, 2 s (line/line)				
Rated temperature T _R	+40 °C				
Rated current I _R	Referred to 50 Hz and rated temperature				
Nominal inductance L _R	Measured with Agilent 4284A at 10 kHz, 0.1 mA, +20 °C Inductance is specified per winding.				
Inductance tolerance	-30/+50% at +20 °C				
Inductance decrease ΔL/L ₀	< 10% at DC magnetic bias with I _R , +20 °C				
Stray inductance L _{stray,typ}	Measured with Agilent 4284A at 10 kHz, 5 mA, +20 °C, typical values				
DC resistance R _{typ}	Measured at +20 °C, typical values, specified per winding				
Solderability (lead free)	Sn96.5Ag3.0Cu0.5: +(245 \pm 3) °C, (3 \pm 0.3) s Wetting of soldering area \geq 95% (to IEC 60068-2-58, test Td ₁ , method 1)				
Resistance to soldering heat	+(260 ±5) °C, (10 ±1) s (to IEC 60068-2-58, test Td ₂ , method 1)				
Climatic category	40/125/56 (to IEC 60068-1)				
Storage conditions (packaged)	–25 °C +40 °C, ≤ 75% RH				
Weight	Approx. 2.5 g				

Characteristics and ordering codes

I _R	L _R mH	L _{stray,typ} μΗ	R_{typ} $m\Omega$	Ordering code
0.3	22	130	1500	B82720S2301N042
0.3	12	80	1100	B82720S2301N040
0.6	4.4	30	400	B82720S2601N040
1.0	3.0	20	220	B82720S2102N040
1.5	1.6	10	110	B82720S2152N040
2.0	1.1	6	65	B82720S2202N040

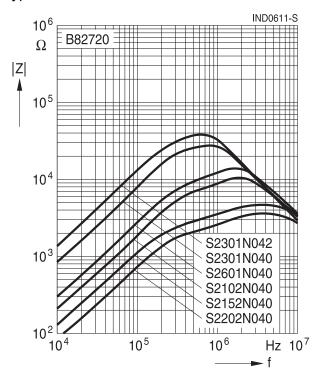


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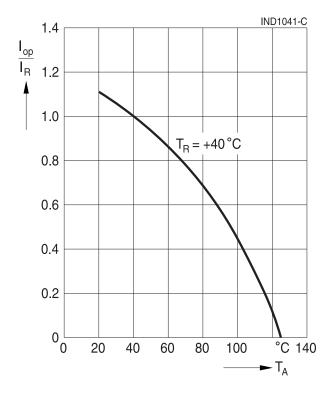


Impedance |Z| versus frequency f

measured with windings in parallel at +20 °C, typical values



Current derating I_{op}/I_R versus temperature T_A



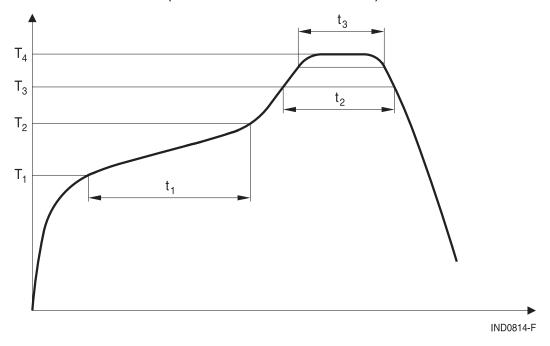


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Recommended reflow soldering profile

Pb-free solder material (based on JEDEC J-STD 020E)



T ₁ °C	T₂	T ₃	T ₄	t ₁	t ₂	t ₃
	°C	°C	°C	s	s	s
150	200	217	245	< 110	< 90	< 30 @ T ₄ –5 °C

Time from +25 °C to T_4 : max 300 s Max. numbers of reflow cycles: 3



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Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition), online catalogs and in the data sheets.
 - Particular attention should be paid to the derating curves, if given. Derating applies in the case the ambient temperature in application exceeds the rated temperature of the component.
 - Ensure the operation temperature of the component in application, not to exceed the maximum specified value or the upper climatic category temperature.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. It is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
 - Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g., ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted, sealed, or varnished in customer applications:
 - Many potting, sealing of varnishing materials shrink as they harden. They therefore exert a
 pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting, sealing or varnishing materials used attacks or destroys the wire insulation, plastics, or glue.
 - The effect of the potting, sealing, or varnishing materials may change the high-frequency behavior of the components.
- Magnetic core materials such as ferrites are sensitive to direct impact. This can cause the core material to flake or lead to breakage of the magnetic core material.
- Any type of tension or pressure on the product may result in damage and affect its functionality and reliability.
 - The products are only to be attached to fixings or mounting holes provided for this purpose in accordance with the data sheet.
 - If additional mechanical forces are applied to the component, e.g., application of gap pads, it
 is necessary to check whether they attack or destroy any part of the component.
 - It is not permitted for the product specified in the data sheet to assume a mechanical function in the final application.
- Inductance value can drop if external metallic or magnetic parts will be put close to the coil or into the air gap of the coil or core or magnetic material.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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